TB1S-15~TB10S-15

Rev.C Feb.-2015

蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

描述 / Descriptions

1.5A 表面贴装玻璃钝化整流桥，薄型 ABS/LBF 封装。
1.5A Surface Mount Glass Passivated Bridge Rectifier, ABS/LBF thin package.

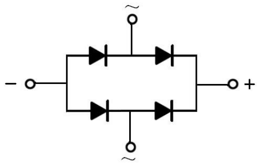
特征 / Features

玻璃钝化芯片，反向电压：100V~1000V，正向电流：1.5A，浪涌电流大，适用表面贴装。无卤产品。
Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V,Forward Current: 1.5A,High Surge Current Capability, Designed for Surface Mount Application. Halogen free product.

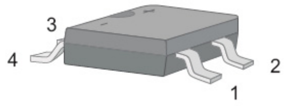
用途 / Applications

一般用途.
General purpose.

内部等效电路 / Equivalent Circuit

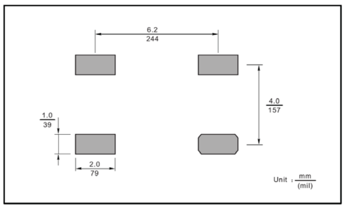


引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25℃)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		TB1S-15	TB2S-15	TB4S-15	TB6S-15	TB8S-15	TB10S-15	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 50℃	I_o	1.5						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50（Typical:55A）						A
Typical Junction Capacitance（Note1）	C_j	25						pF
Typical Thermal Resistance（Note2）	$R_{\theta JA}$	70						℃/W
	$R_{\theta JL}$	16						℃/W
Junction Temperature, Storage Temperature Range	T_j, T_{stg}	-55~150						℃

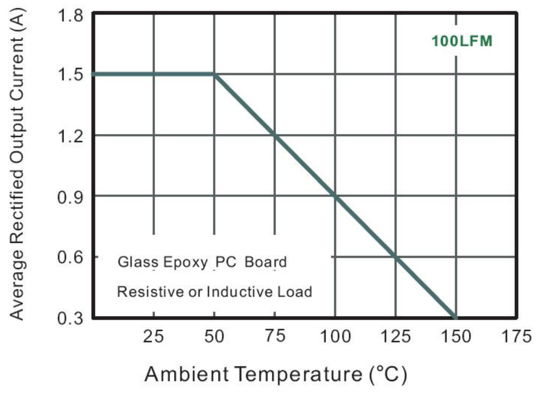
Note:

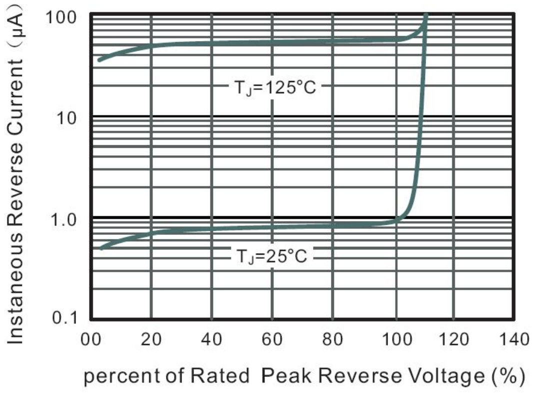
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×2.54mm^2 copper pad..

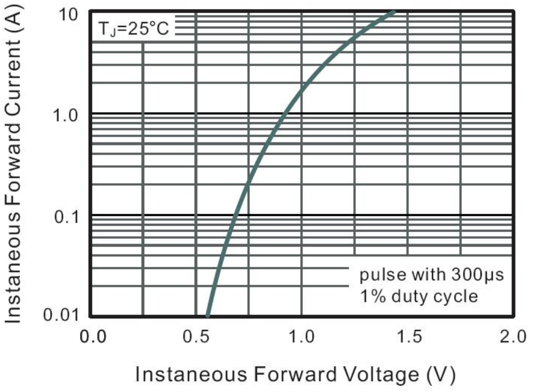
电性能参数 / Electrical Characteristics(Ta=25℃)

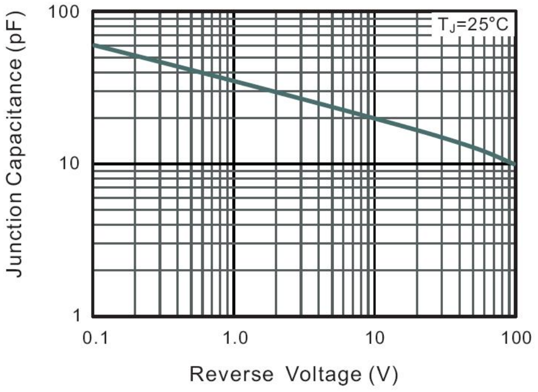
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	V_F	I_F=1.5A	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25℃	5.0	μA
		T_a=125℃	100	μA

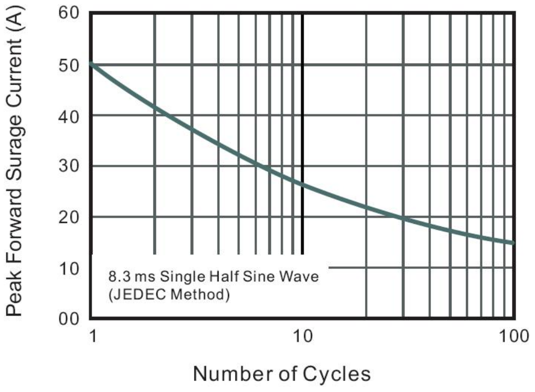
电参数曲线图 / Electrical Characteristic Curve





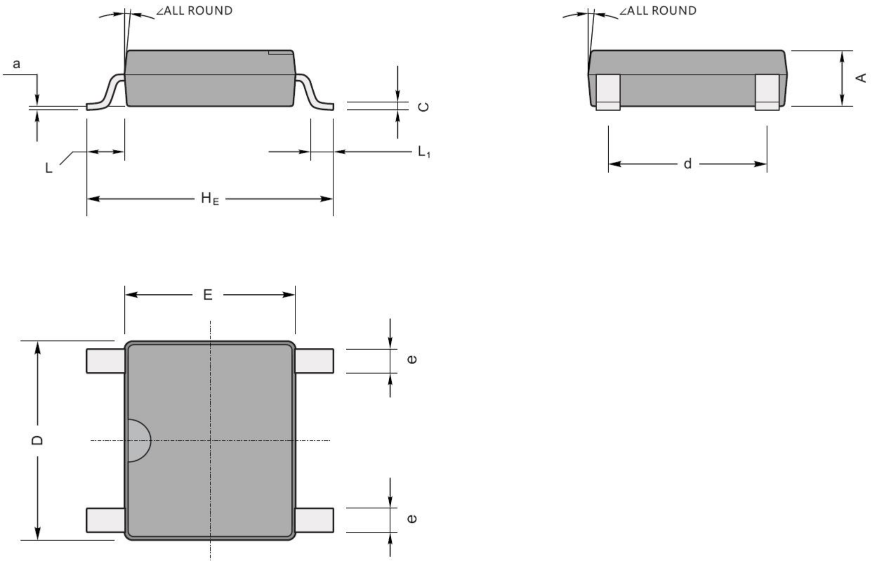






外形尺寸图 / Package Dimensions

ABS/LBF

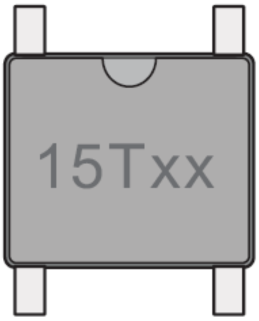


ABS/LBF mechanical data

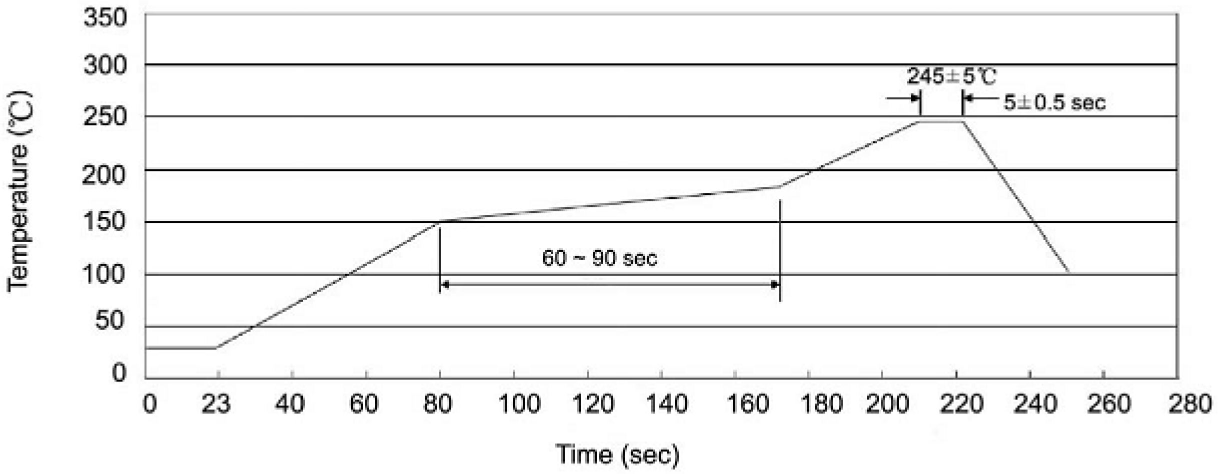
UNIT		A	C	D	E	H_E	d	e	L	L_1	a	∠
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	59	8.7	205	177	252	165	28	37	24	4	
	min	51	5.9	193	166	236	150	20				

印章说明 / Marking Instructions

Marking

Type number	Marking code
TB1S-15	15T1
TB2S-15	15T2
TB4S-15	15T4
TB6S-15	15T6
TB8S-15	15T8
TB10S-15	15T10
	

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：	Note:
1、预热温度 25 ~ 150℃，时间 60 ~ 90sec;	1.Preheating:25~150℃, Time:60~90sec.
2、峰值温度 245±5℃，时间持续为 5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3、焊接制程冷却速度为 2 ~ 10℃/sec.	3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃　　时间：10±1 sec.　　Temp.:260±5℃　　Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ABS/LBF	5000	2	10000	5	50000	13″ ×15	336X336X40	345X345X235

使用说明 / Notices